

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

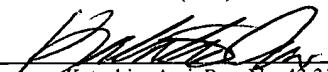
Applicant : Matsumura, et al.
Appl. No. : Unknown
Filed : Unknown
For : DICING/DIE-BONDING FILM,
METHOD OF FIXING CHIPPED
WORK AND SEMICONDUCTOR
DEVICE
Examiner : Unknown
Group Art Unit : Unknown

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 3, 2003

(Date)


Katsuhiro Arai, Reg. No. 43,315

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Preliminary to examination on the merits, please amend the above-captioned application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.